

Product Summary

V_{RRM} (V)	I_o (A)	$V_F(MAX)$ (V) @ +25°C	$I_R(MAX)$ (mA) @ +25°C
60	25	0.6	0.15

Description and Applications

Packaged in the compact thermally efficient POWERDI5060-8 package, the SBRT25M60SLP provides low forward voltage and excellent reverse leakage stability at high temperatures. It is ideal for use as a rectifier, freewheel diode or blocking diode in:

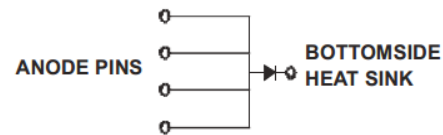
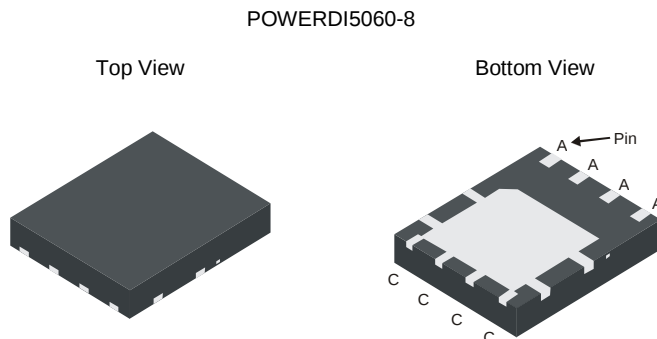
- DC-DC Converters
- AC-DC Adaptors

Features and Benefits

- Reduced low forward voltage drop (V_F) and reverse leakage (I_R); better efficiency and cooler operation
- Reduced high temperature reverse leakage; Increased reliability against thermal runaway failure in high temperature operation
- Less than 1.1mm package profile – ideal for thin applications
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free “Green” Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: POWERDI5060-8
- Case Material: Molded Plastic, “Green” Molding compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Below
- Weight: 0.097 grams (approximate)



Note: All four anode pins must be electrically connected at the printed circuit board.

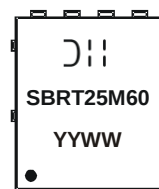
Ordering Information (Note 4)

Part Number	Case	Packaging
SBRT25M60SLP-13	POWERDI5060-8	2500/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, “Green” and Lead-free.
 3. Halogen- and Antimony-free “Green” products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

POWERDI5060-8



SBRT25M60 = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 14 = 2014)
WW = Week (01-53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	60	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
Average Rectified Output Current	I _O	25	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	220	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	10	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R _{θJC}	1	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop (Note 6)	V _F	—	0.45	0.52	V	I _F = 12.5A, T _J = +25°C
			0.54	0.6		I _F = 25A, T _J = +25°C
			—	0.58		I _F = 25A, T _J = +125°C
			—	—		I _F = 25A, T _J = +150°C
Leakage Current (Note 6)	I _R	—	35	150	μA	V _R = 60V, T _J = +25°C
		—	—	50	mA	V _R = 60V, T _J = +125°C

Notes: 5. Test with additional heatsink, (Al substrate with copper pad 30mm*30mm + Black Aluminum 80mm*48mm*35mm)
 6. Short duration pulse test used to minimize self-heating effect.

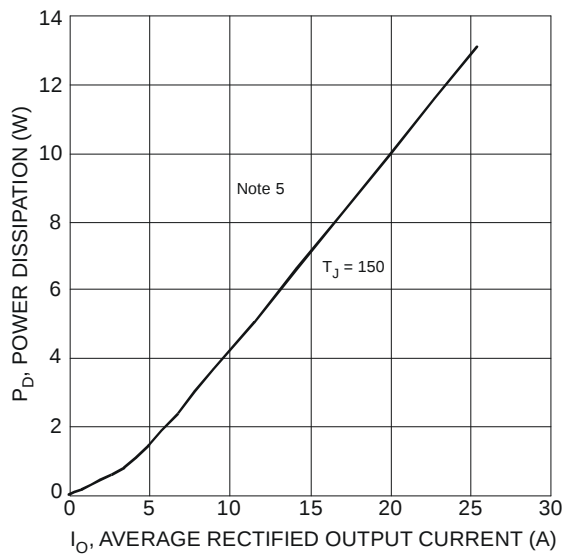


Figure 1 Forward Power Dissipation

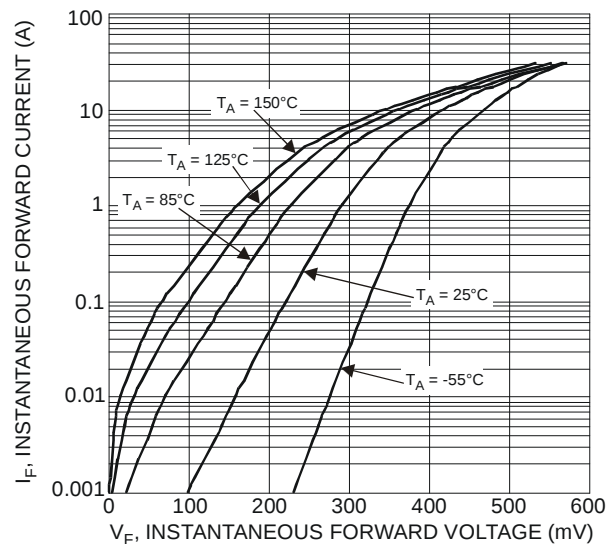
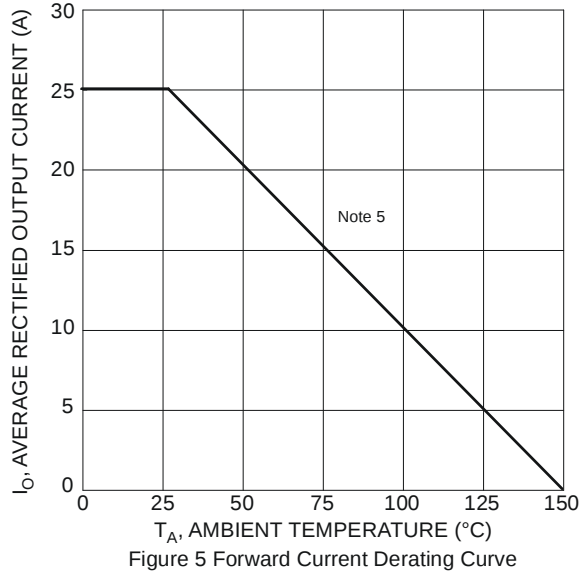
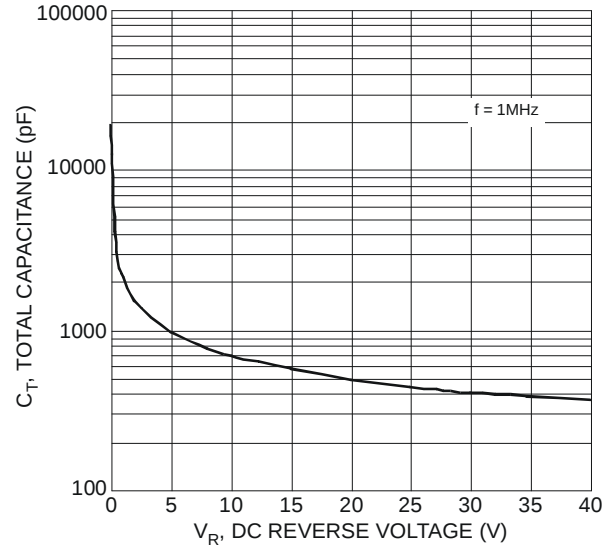
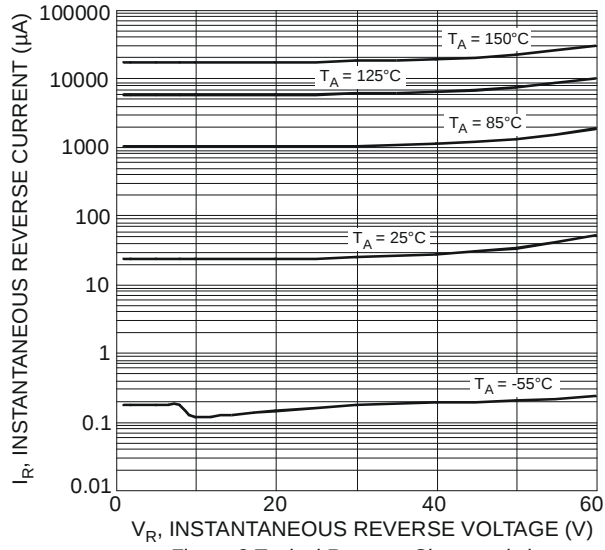
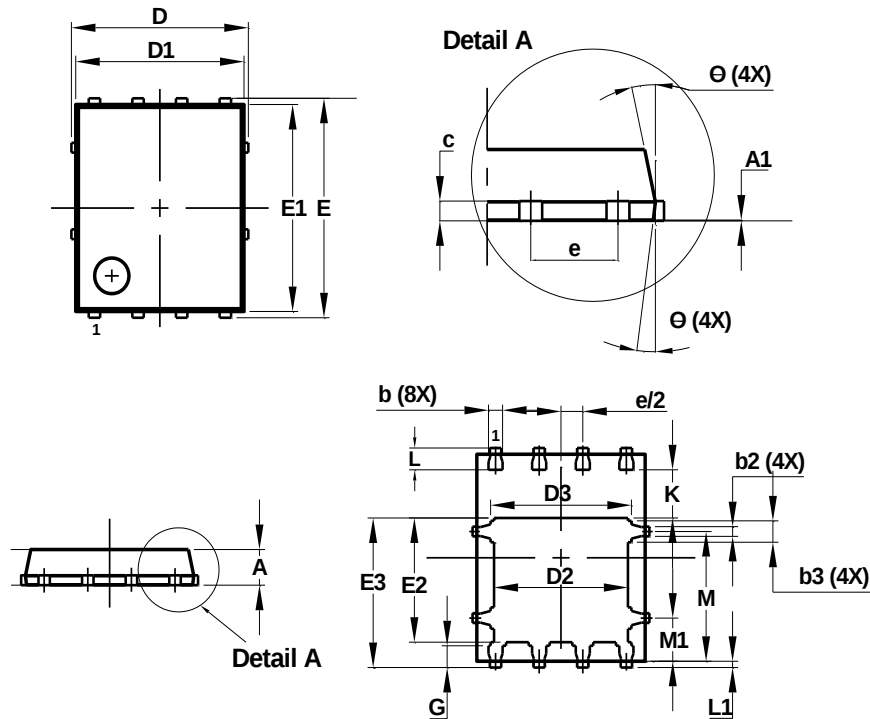


Figure 2 Typical Forward Characteristics



Package Outline Dimensions

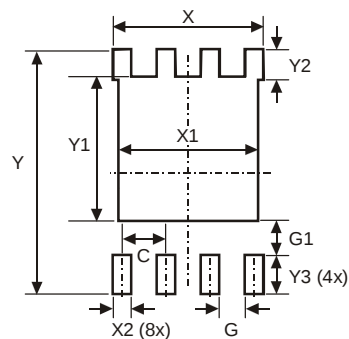
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



POWERDI5060-8			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	—
b	0.33	0.51	0.41
b2	0.200	0.350	0.273
b3	0.40	0.80	0.60
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.70	4.10	3.90
D3	3.90	4.30	4.10
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	3.28	3.68	3.48
E3	3.99	4.39	4.19
e	1.27 BSC		
G	0.51	0.71	0.61
K	0.51	—	—
L	0.51	0.71	0.61
L1	0.1	0.20	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
Θ	10°	12°	11°
Θ1	6°	8°	7°
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	4.420
X1	4.100
X2	0.610
Y	6.610
Y1	3.810
Y2	1.020
Y3	1.270

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